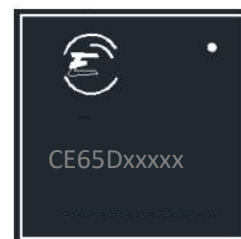
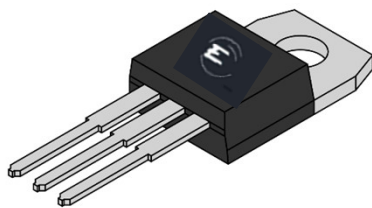




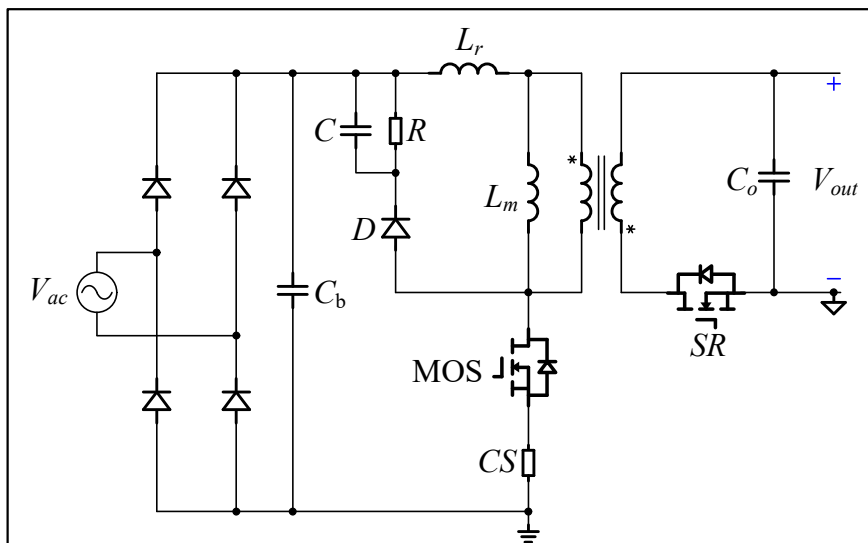
能华半导体

反激主开关损耗分析



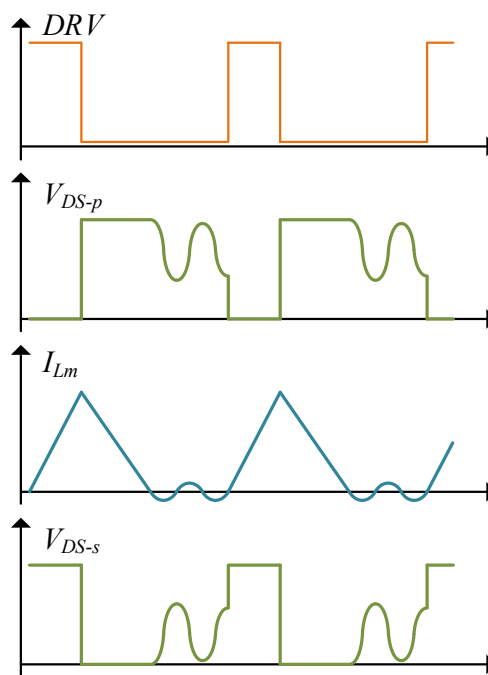
江苏能华微电子科技发展有限公司

- ◆ 反激模式分类 ----- 3
- ◆ QR反激主开关损耗分析 ----- 4
- ◆ CCM反激主开关损耗分析 ----- 5

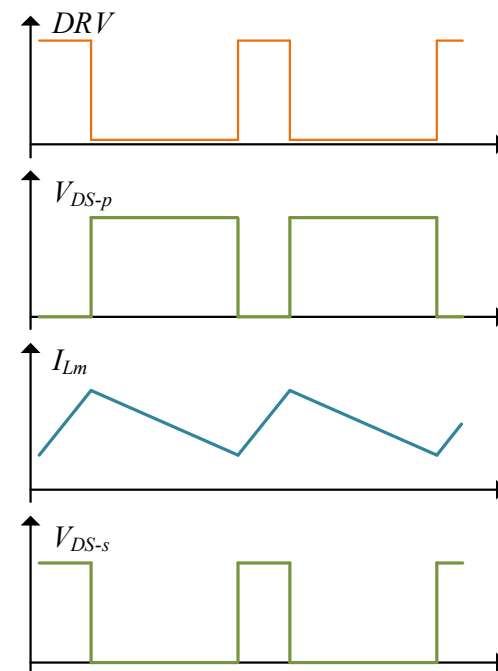


Flyback Converter

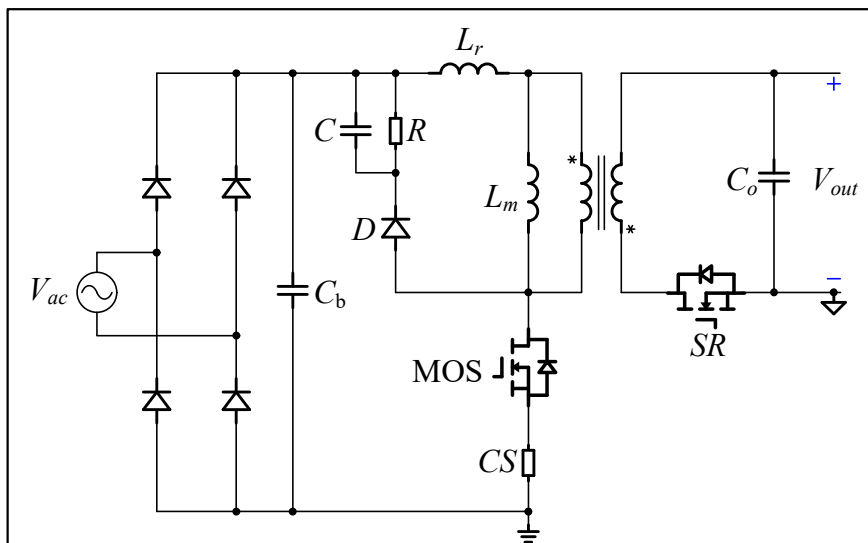
QR 模式



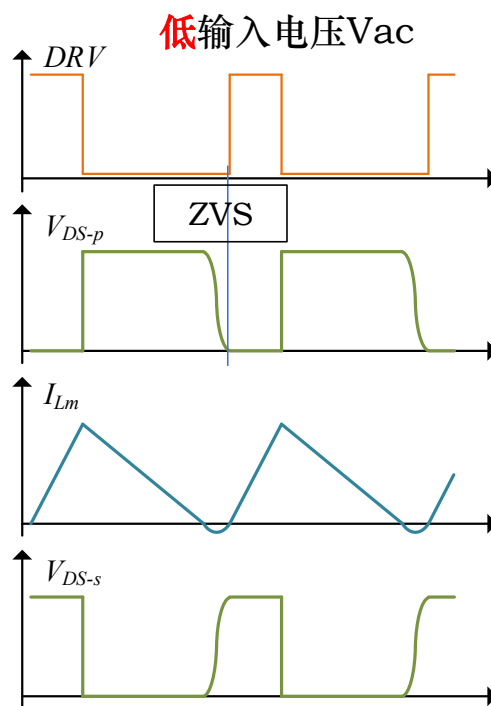
CCM 模式



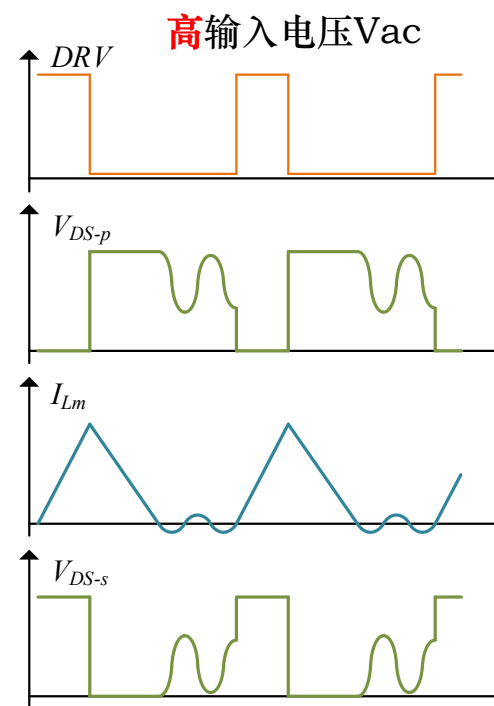
QR反激-主开关MOS的损耗



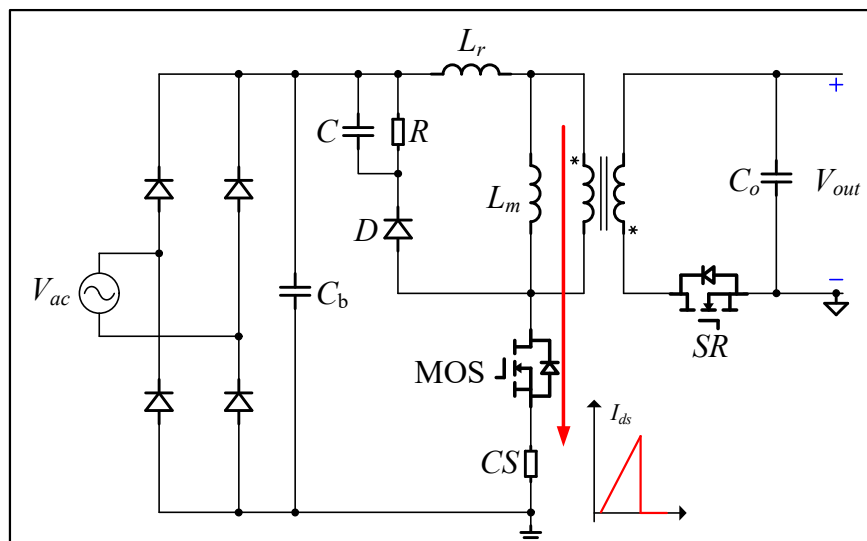
QR Mode Flyback



通态损耗, 关断损耗, 驱动损耗

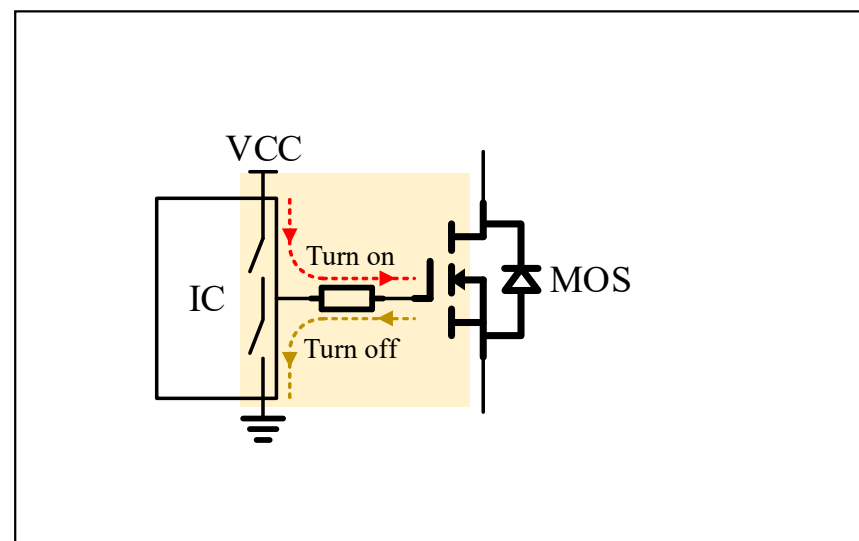


通态损耗, 关断损耗, 驱动损耗, **开通损耗**



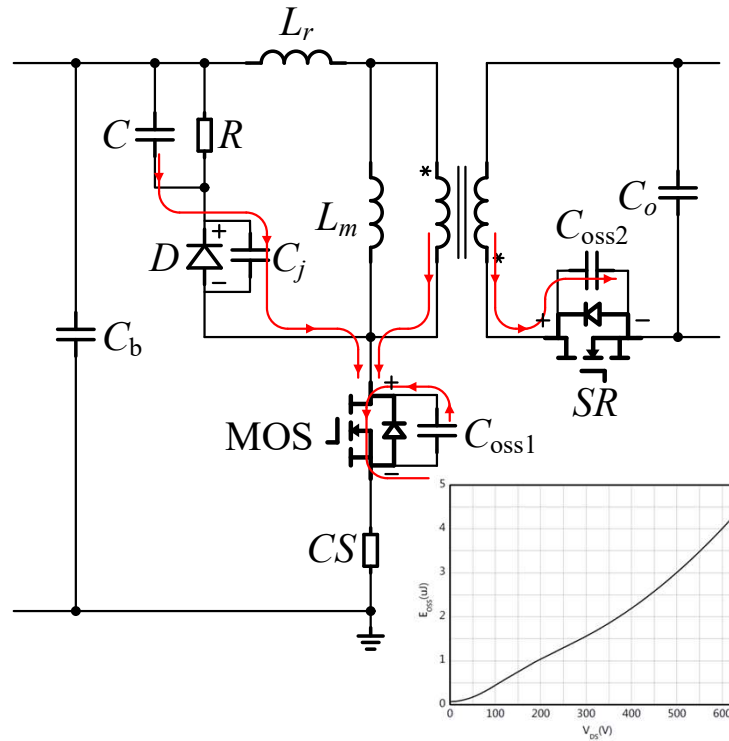
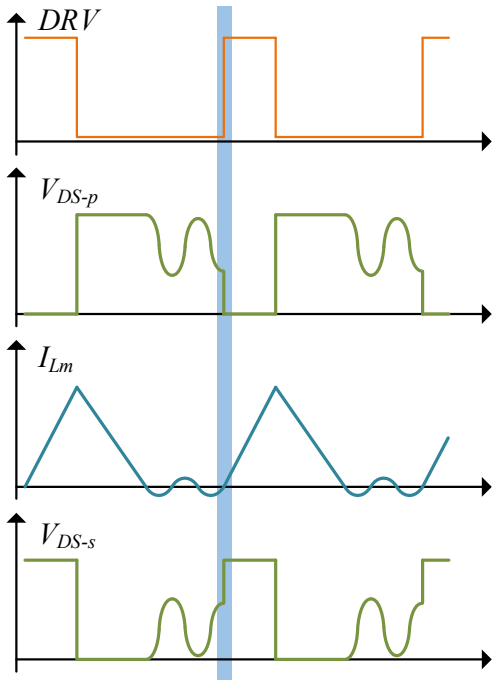
导通损耗

$$P_{con} = I_{rms}^2 * R_{on} \quad I_{rms} = \frac{\sqrt{3}}{3} * I_p * Duty$$



驱动损耗

$$P_{drv} = Freq * VCC * Q_g$$



开通前:

- 主MOS的压降 $V_{ds} = V_1$
- RCD支路压降为 $V_{bus} - V_1$
- SR的压降 $V_{ds} = (V_{bus} - V_1) / n + V_o$

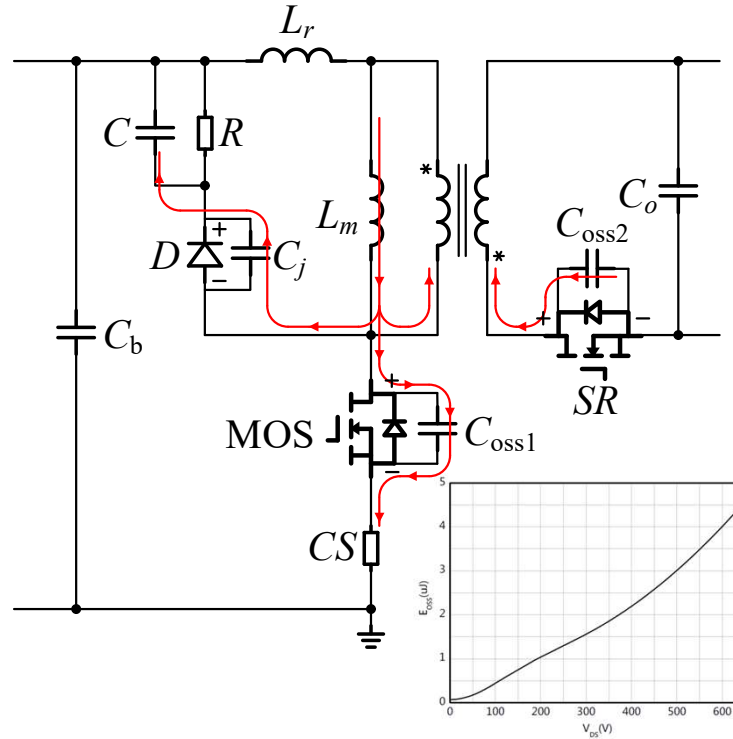
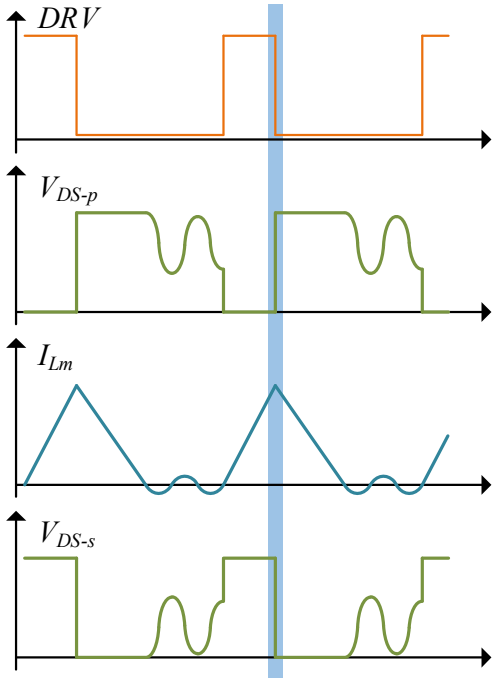
开通后:

- 主MOS的压降 $V_{ds} = 0$
- RCD支路压降为 V_{bus}
- SR的压降 $V_{ds} = V_{bus} / n + V_o$

开通损耗
$$P_{on} = Freq * \left(\int V_{ds} * I_d * dt + E_{oss} \right)$$

开通时，RCD和SR的寄生容(结电荷)的电流叠加到主MOS的Id，增加MOS的IV交叠损耗（零电流开通时的**电流尖峰**）

QR反激-主开关MOS的损耗



关断前:

主MOS的压降 $V_{ds}=0$

RCD支路压降为 V_{bus}

SR的压降 $V_{ds}=V_{bus}/n + V_o$

关断后:

主MOS的压降 $V_{ds}= V_{bus}+nV_o$

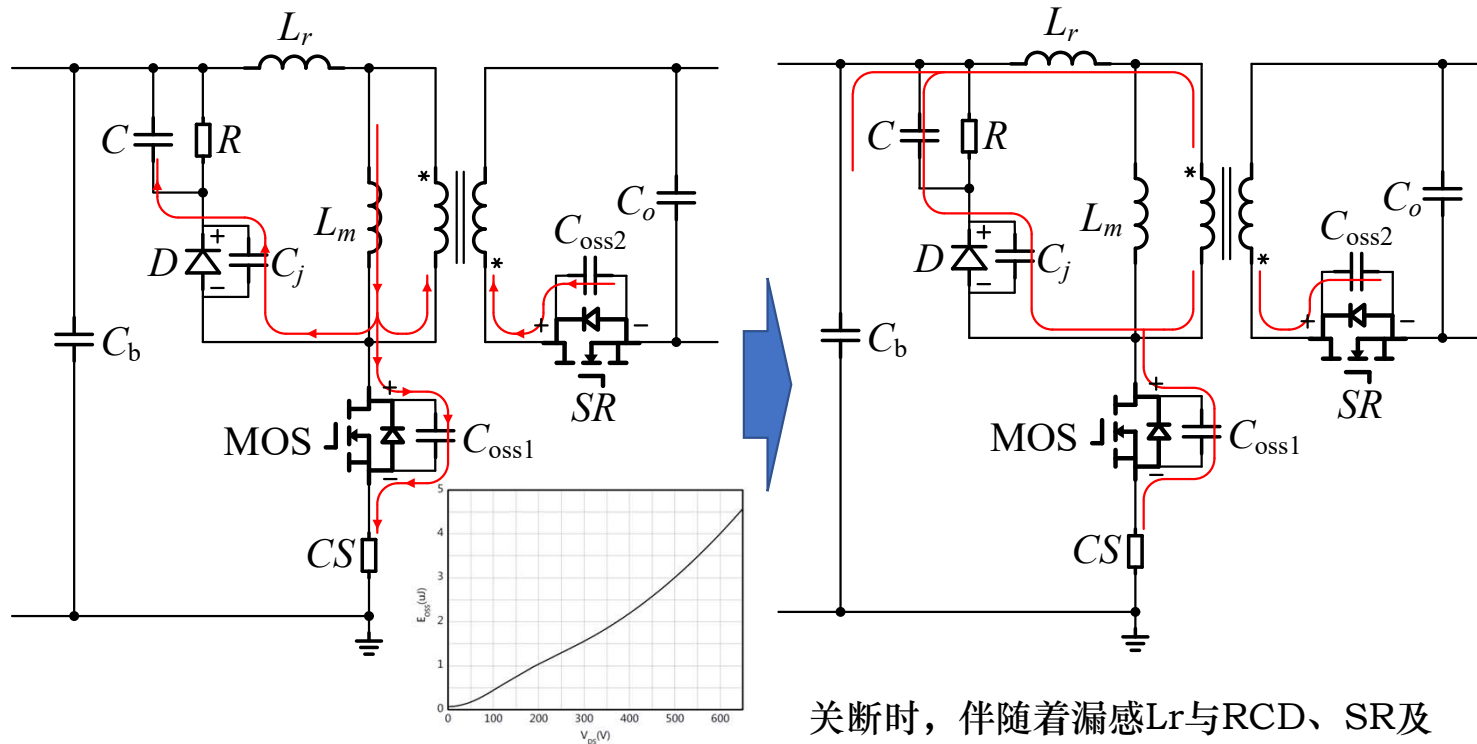
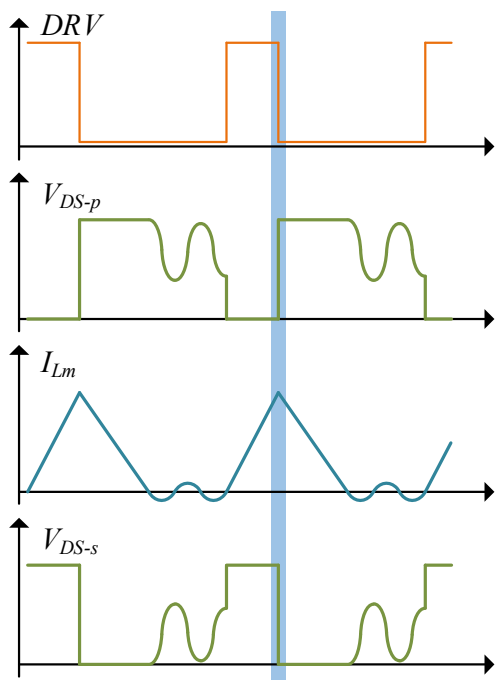
RCD支路压降为 $-nV_o$

SR的压降 $V_{ds}=0$

关断时，励磁电流 I_{Lm} 给RCD、SR及主MOS的寄生容充电/放电，较大的寄生容会增加关断过程的时间

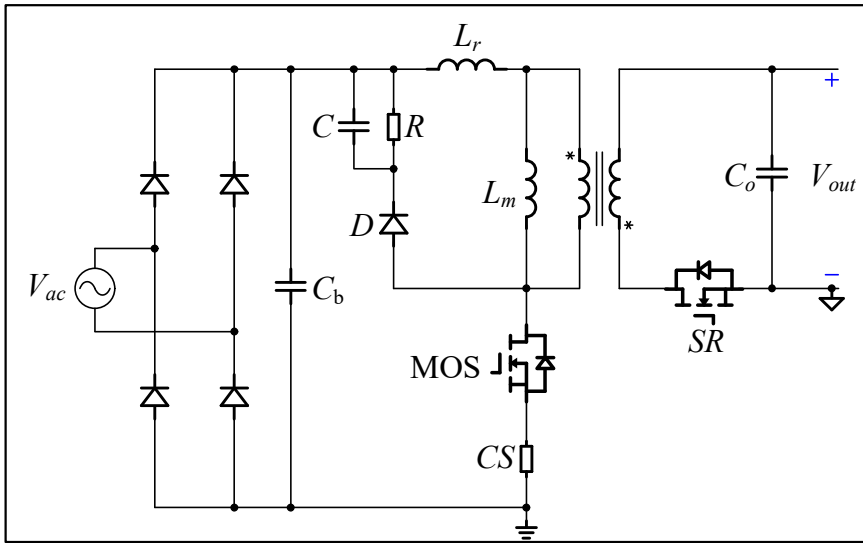
关断损耗
$$P_{off} = Freq * \left(\int V_{ds} * I_d * dt - E_{oss} \right)$$

QR反激-主开关MOS的损耗

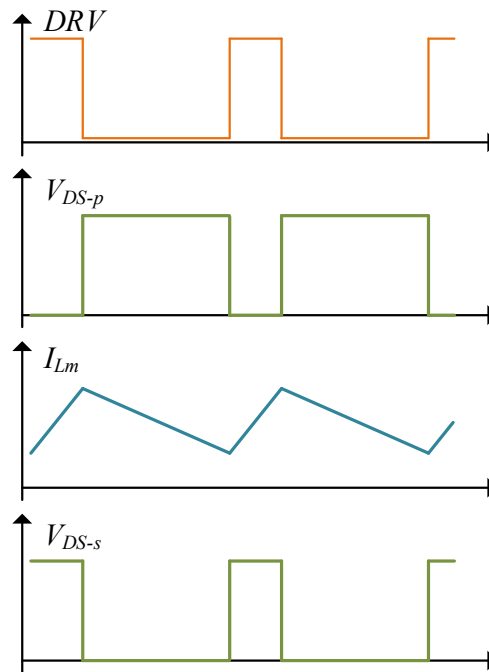


关断时，伴随着漏感 L_r 与RCD、SR及主MOS的寄生容高频振荡的过程，导致主MOS较大的尖峰电压

$$\text{关断损耗 } P_{\text{off}} = \text{Freq} * \left(\int V_{ds} * I_d * dt - E_{\text{oss}} \right)$$



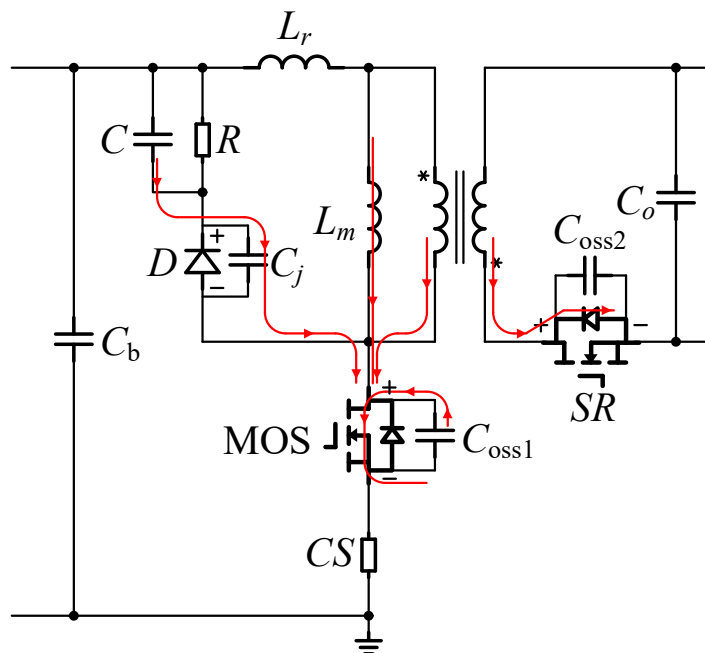
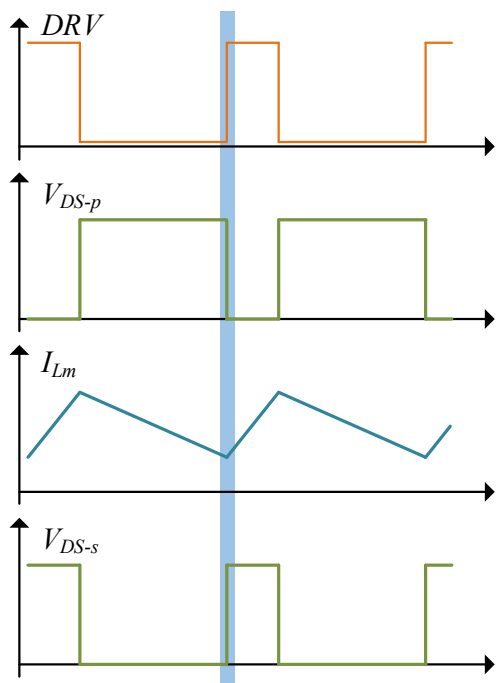
CCM Flyback



通态损耗, 关断损耗, 驱动损耗,
开通损耗

通态损耗, 关断损耗, 驱动损耗,
 三者本质上和QR模式下的没有
 差别;
开通损耗略有不同;

CCM反激-主开关MOS的损耗



开通前:

主MOS的压降 $V_{ds} = V_{bus} + nV_o$

RCD支路压降为 nV_o

SR的压降 $V_{ds} = -0.7V$

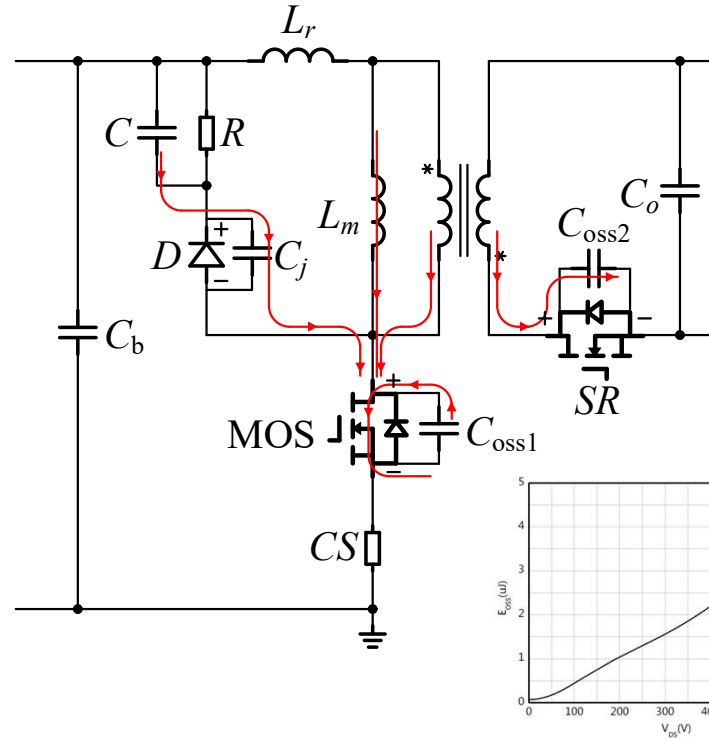
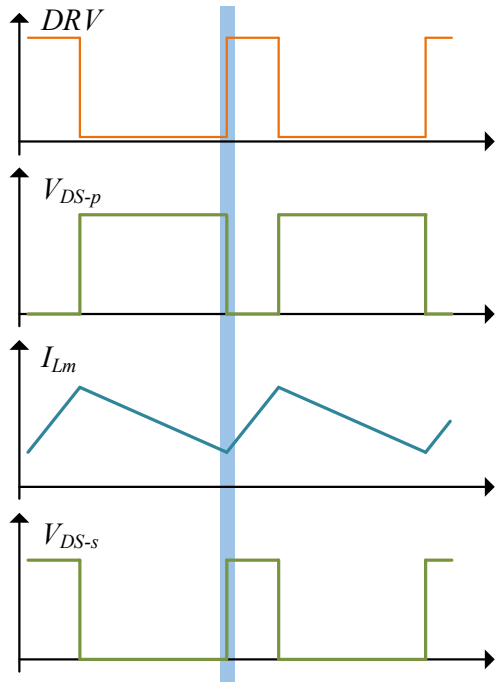
二极管反向恢复期间:

主MOS的压降 $V_{ds} = V_{bus} + nV_o$

RCD支路压降为 nV_o

SR的压降 $V_{ds} = 0V$

SR反向恢复造成主MOS开通损耗 $P_{on1} = Freq * (V_{bus} + nV_o) * Q_{rr}$



二极管反向后:

主MOS的压降 $V_{ds} = V_{bus} + nV_o$

RCD支路压降为 nV_o

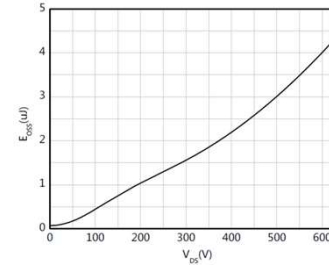
SR的压降 $V_{ds} = 0V$

开通过程结束:

主MOS的压降 $V_{ds} = 0$

RCD支路压降为 V_{bus}

SR的压降 $V_{ds} = V_{bus}/n + V_o$



总开通损耗
$$P_{on} = Freq * \left(\int V_{ds} * I_d * dt + E_{oss} \right)$$

开通时, RCD和SR的寄生容(结电荷)的电流以及SR的BD反向恢复电流叠加到主MOS的Id, 增加MOS的IV交叠损耗